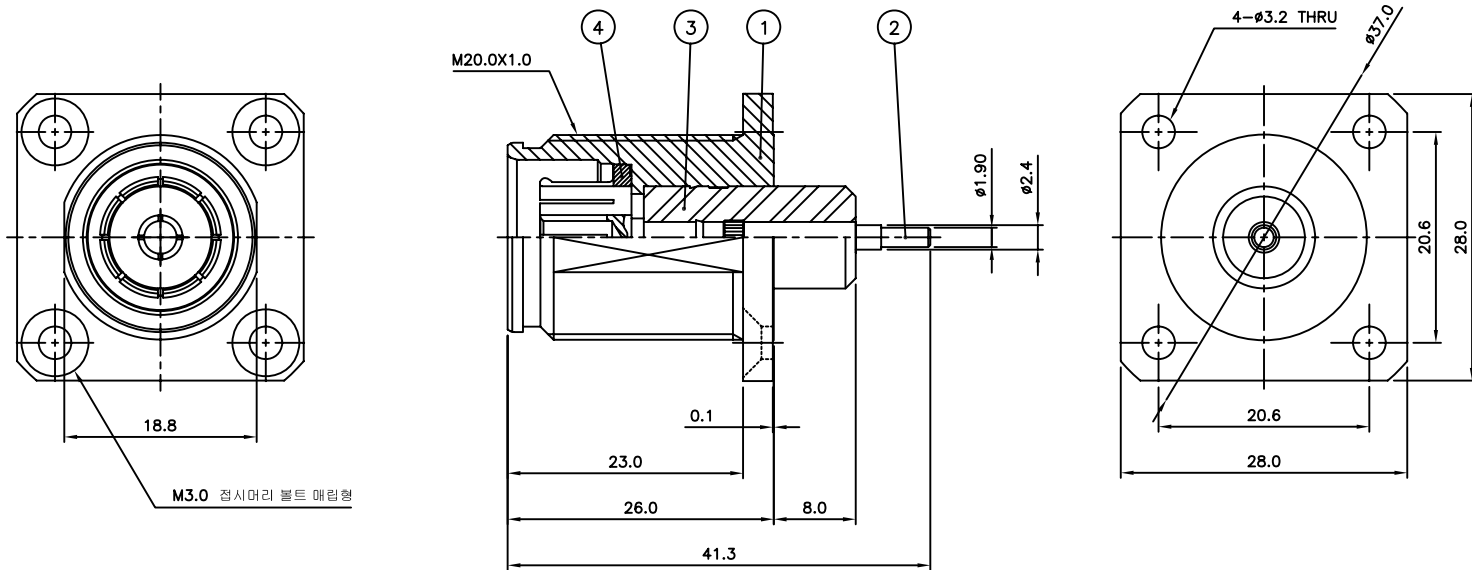


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
1	Initial Registration	S.L.SON	J.H.YOUN	2019.07.16.
2	조립공차 ±0.1 -> ±0.2 변경	S.Y.EUN	I.C.KIM	2020.05.12.



M3.0 점시머리 볼트 매립형

4	JACK	1	M8sBD C3604BD-F	Silver Plate (3μm)	DJA00228-5/6
3	INSULATOR	1	TEFLON		DIN03063-N/1
2	CONTACT	1	BaCu C17300	Silver Plate (5μm)	DCT04032-5/1
1	BODY	1	M8sBD C3604BD-F	SUCO Plate (3μm)	DBD04187-5/4
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE	2020. 05. 12.
	Angle	APPROVED BY	I.C.KIM
MATERIAL	FINISH	CHECKED BY	
		DRAWN BY	S.Y.EUN
FINISH	SCALE	UNIT	mm
	2/1		

RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
KJ COMTECH KJ COMTECH CO., LTD.	
TITLE 4.3-10 JS-4H Solder END	
DWG NO.	CN03855-7/1
REVISION	2
SHEET	1 of 1